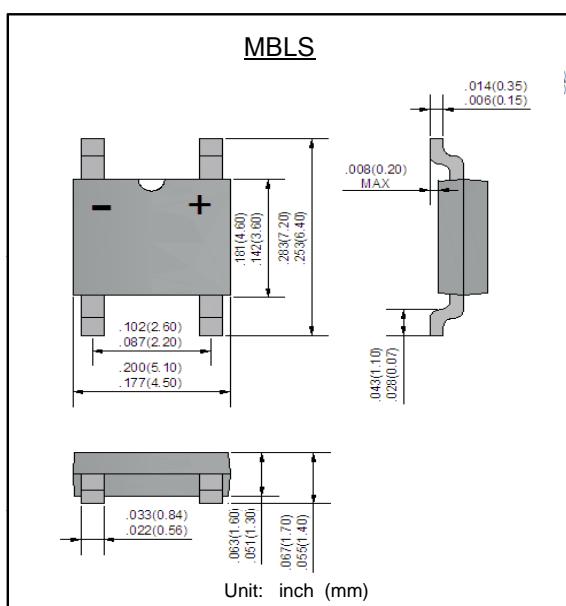


表面安装桥式整流器
反向电压 200 ~ 1000 V
正向电流 0.8 A

Surface Mount Bridge Rectifiers
Reverse Voltage 200 ~ 1000 V
Forward Current 0.8 A



特征 Features

- 反向漏电流低 Low reverse leakage
- 正向浪涌承受能力强 High forward surge capability
- 玻璃钝化芯片 Glass passivated chip
- 高温焊接保证 High temperature soldering guaranteed: 260°C/10 秒 260°C/10seconds
- 引线和管体皆符合RoHS标准。 Lead and body according with RoHS standard

机械数据 Mechanical Data

- 封装: MBLS 塑料封装 Case: MBLS Molded plastic
- 极性: 标记模压或印于本体 Polarity: Symbols molded or marked on body
- 安装位置: 任意 Mounting Position: Any

最大值和特性 TA = 25°C 除非另有规定。

Maximum Ratings & Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

参数 Parameter	符号 Symbols	MBL2S	MBL4S	MBL6S	MBL8S	MBL10S	单位 Unit	
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V	
最大均方根电压 Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V	
最大直流阻断电压 Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V	
最大正向平均整流电流 (Note 1) TA= 25°C Maximum average forward rectified current	I _{F(AV)}	0.8					A	
最大正向平均整流电流 (Note 2) TA= 25°C Maximum average forward rectified current	I _{F(AV)}	0.5					A	
正向不重复浪涌电流 10 ms单一正弦半波 Non-repetitive peak forward surge current 10 ms singlehalf sine-wave	I _{FSM}	35					A	
最大正向电压 @IF=0.4A Maximum forward voltage	V _F	1.0					V	
最大反向电流 @V _{DC} TA = 25°C Maximum reverse current	I _R	5					μA	
典型热阻 Typical thermal resistance (Note 3)	R _{θJA}	76					°C/W	
典型热阻 Typical thermal resistance (Note 4)	R _{θJA}	134						
典型热阻 Typical thermal resistance (Note 5)	R _{θJL}	20						
工作结温和存储温度 Operating junction and storage temperature rang	T _j , T _{STG}	-55 --- +150					°C	

备注 Note:

- 1) 安装在氧化铝基板上 On alumina substrate
- 2) 安装在玻璃-环氧基板上 On glass-epoxy substrate
- 3) 结和环境之间 , 安装在氧化铝基板上 Between junction and ambient, On alumina substrate
- 4) 结和环境之间 , 安装在玻璃-环氧基板上 Between junction and ambient, On glass-epoxy substrate
- 5) 结和引线之间 Between junction and lead

特性曲线 Characteristic Curves

